

031123 US

App No.: NEW
 Inventor: Takamitsu MIKUNI et al.
 Title: THERMALLY CONDUCTIVE PRESSURE-SENSITIVE ADHESIVE
 COMPOSITION, THERMALLY CONDUCTIVE SHEET-FORM MOLDED
 FOAM, AND PROCESS FOR PRODUCING THE SAME
 NEW SHEET

Docket No.: 4670-0128PUS1

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FIG. 1

